

Bill of Materials

TI DESIGNS

TIDC-Bluetooth-low-energy-Light

Part Reference	Quantity	Value	PCB Package	Description	MPN	Manufacturer
C3	1	1uF	0603	CAPACITORS, CERAMIC, 1uF, 15%, X5R, 10V, 0603, SMD	GRM188R61A105KA61D	MURATA
C21 C31	2	47pF	0402	CAPACITOR, CERAMIC COG/NPO, 47pF, 50V, -5%/+5%, -55DEGC/+125DEGC, 0402, SMD	CAPACITOR_0402_47pF_COG/NPO_M_+/-5%_50V	MANUFACTURER SELECTION
C41 C42	2	4.7uF	0603	CAPACITOR, CERAMIC X5R, 4.7uF, 6.3V, -10%/+10%, -55DEGC/+85DEGC, 0603, SMD	GRM188R60J475KE19D	MURATA
C101 C241 C271 C311	4	100nF	0402	CAPACITOR, CERAMIC X7R, 100nF, 6.3V, -10%/+10%, -55DEGC/+125DEGC, 0402, SMD	GRM155R70J104KA01D	MURATA
C211 C391 C401	3	1uF	0402	CAPACITOR, CERAMIC X5R, 1uF, 10V, -10%/+10%, -55DEGC/+85DEGC, 0402, SMD	GRM155R61A105KE15D	MURATA
C221 C231	2	15pF	0402	CAPACITOR, CERAMIC COG/NPO, 15pF, 50V, -5%/+5%, -55DEGC/+125DEGC, 0402, SMD	GRM1555C1H150JA01D	MURATA
C251 C261	2	1.5pF	0402	CAPACITOR, CERAMIC COG/NPO, 1.5pF, 50V, -0.25pF/+0.25pF, -55DEGC/+125DEGC, 0402, SMD	GRM1555C1H1R5CA01D	MURATA
C272	1	1220pF	0402	CAPACITOR, CERAMIC COG/NPO, 220pF, 50V, -5%/+5%, -55DEGC/+125DEGC, 0402, SMD	GRM1555C1H221JA01D	MURATA
C392	1	22pF	0402	CAPACITOR, CERAMIC COG/NPO, 22pF, 50V, -5%/+5%, -55DEGC/+125DEGC, 0402, SMD	GRM1555C1H220JA01D	MURATA
C393	1	10uF	0603	CAPACITOR, CERAMIC X5R, 10uF, 6.3V, -20%/+20%, -55DEGC/+85DEGC, 0603, SMD	GRM188R60J106ME47D	MURATA
C394 C395	2	18pF	0402	CAPACITOR, CERAMIC COG/NPO, 18pF, 50V, -55DEGC/+125DEGC, 0402, SMD	GRM1555C1H180JA01D	MURATA
CR1	1	LA CP7P		OPTO, LED, 2.6V, 0.35A, SMD	LA CP7P	OSRAM OPTO SEMICONDUCTORS
CR2	1	LD CP7P		OPTO, LED, 3.7V, 0.35A, SMD	LD CP7P	OSRAM OPTO SEMICONDUCTORS
CR3	1	LT CP7P		OPTO, LED, 3.5V, 0.35A, SMD	LT CP7P	OSRAM OPTO SEMICONDUCTORS
CR4	1	LUW CP7P		OPTO, LED, 3.75V, 0.35A, SMD	LUW CP7P	OSRAM OPTO SEMICONDUCTORS
FB1	1	BLM15HG102SN1	0402	FILTER, INDUCTOR TYPE, 1000OHM@100MHZ, 25%,250mA, 0402, SMD	BLM15HG102SN1D	MURATA
J2	1	1981568-1		CONNECTOR, USB-B, 5 PINS, PITCH 0.65mm, SMD	1981568-1	Tyco
L251	1	3.9nH	0402	INDUCTOR, CHIP, 3.9nH, -0.3nH/+0.3nH, 0.3A, -55DEGC/+125DEGC, 0402, SMD	LQG15HS3N9S02D	MURATA
L262	1	2.2uH	1008	INDUCTOR, CHIP, 2.2uH, -20%/+20%, 1A, -55DEGC/+125DEGC, 1008, SMD	LQM2HPN2R2MJ0L	MURATA
LBL1	1	HOT_SURFACE_LABEL		LABEL, HOT SURFACE LABEL		
M1	1	F12237_OSLO-CLUSTER-W		MECHANIC, LENS ARRAY, NOT APPLY	F12237_OSLO-CLUSTER-W	LEDIL
P1	1	FTSH-105-01-F-DV-K		CONNECTOR, HEADER, MALE, STRAIGHT, 10 PINS, 2 ROWS, PITCH 1.27mm, SMD	FTSH-105-01-F-DV-K	SAMTEC
Q1 Q2 Q3 Q4	4	BC817-16	SOT23-3	TRANSISTOR, BIPOLAR NPN, 45V, 0.5A, 0.25W, SOT23-3, SMD	BC817-16.215	NXP
R1	1	560	0402	RESISTOR, THICK FILM, 560, -5%/+5%, 0.063W, 50V, -55DEGC/+155DEGC, 0402, SMD	RESISTOR_0402_560_+/-5%_50V_0.063W_M_+/-200PPM	MANUFACTURER SELECTION
R2 R3 R4	3	1k	0402	RESISTOR, THICK FILM, 1k, -5%/+5%, 0.063W, 50V, -55DEGC/+155DEGC, 0402, SMD	RESISTOR_0402_1k_+/-5%_50V_0.063W_M_+/-200PPM	MANUFACTURER SELECTION
R5	1	DNM		RESISTOR, DO NOT MOUNT, 0402, SMD	DNM	
R21 R31	2	33	0402	RESISTOR, THICK FILM, 33, -1%/+1%, 0.063W, 50V, -55DEGC/+155DEGC, 0402, SMD	RK73H1ETTP33R0F	KOA SPEER
R32 R74 R75 R78 R79	5	1.5k	0402	RESISTOR, THICK FILM, 1.5k, -1%/+1%, 0.063W, 50V, -55DEGC/+155DEGC, 0402, SMD	RK73H1ETTP1501F	KOA SPEER
R41	1	2	0402	RESISTOR, THICK FILM, 2, -1%/+1%, 0.063W, 50V, -55DEGC/+155DEGC, 0402, SMD	RK73H1ETTP2R00F	KOA SPEER
R45	1	820k	0402	RESISTOR, THICK FILM, 820k, -1%/+1%, 0.063W, 50V, -55DEGC/+155DEGC, 0402, SMD	RESISTOR_0402_820k_+/-1%_50V_0.063W_M_+/-100PPM	Manufacturer selection
R46	1	160k	0402	RESISTOR, THICK FILM, 160k, -5%/+5%, 0.063W, 50V, -55DEGC/+155DEGC, 0402, SMD	RESISTOR_0402_160k_+/-5%_50V_0.063W_M_+/-200PPM	Manufacturer selection
R64	1	2.7	1206	RESISTOR, THICK FILM, 2.7, -5%/+5%, 0.25W, 200V, -55DEGC/+155DEGC, 1206, SMD	RESISTOR_1206_2.7_+/-5%_200V_0.25W_M_+/-200PPM	Manufacturer selection
R65 R66 R67	3	1	1206	RESISTOR, THICK FILM, 1, -5%/+5%, 0.25W, 200V, -55DEGC/+155DEGC, 1206, SMD	RESISTOR_1206_1_+/-5%_200V_0.25W_M_+/-200PPM	Manufacturer selection
R69	1	56k	0402	RESISTOR, THICK FILM, 56k, -1%/+1%, 0.063W, 50V, -55DEGC/+155DEGC, 0402, SMD	RESISTOR_0402_56k_+/-1%_50V_0.063W_M_+/-100PPM	MANUFACTURER SELECTION
R70	1	6.8k	0402	RESISTOR, THICK FILM, 6.8k, -5%/+5%, 0.063W, 50V, -55DEGC/+155DEGC, 0402, SMD	RESISTOR_0402_6.8k_+/-5%_50V_0.063W_M_+/-200PPM	Manufacturer selection
R71 R72 R73	3	1.2k	0402	RESISTOR, THICK FILM, 1.2k, -5%/+5%, 0.063W, 50V, -55DEGC/+155DEGC, 0402, SMD	RESISTOR_0402_1.2k_+/-5%_50V_0.063W_M_+/-200PPM	Manufacturer selection
R76	1	DNM	0402	RESISTOR, DO NOT MOUNT, 0402, SMD	DNM	DO NOT MOUNT
SW1	1	1188E-1W2-V		SWITCH, TACT, 0.05A@250VAC, 0.05A@12VDC, 0.05A, 250V, PTH	1188E-1W2-V	DIPTRONICS
U1	1	CC2540F256	VQFN40	IC, DIGITAL WIRELESS, 2.4-GHz BLUETOOTH® LOW ENERGY SYSTEM-ON-CHIP, 256 KB, 2V TO 3.3V, SOT23-5	CC2540F256RHAR	TEXAS INSTRUMENTS
U3	1	TPS76933	SOT23-5	IC, ANALOG, ULTRALOW-POWER LINEAR REGULATORS, VIN:32.7V TO 10V, VOUT: 3.3V, SOT23-5	TPS76933DBVT	TEXAS INSTRUMENTS
U4	1	TPS62290	SON6	IC, ANALOG, 1A STEP DOWN CONVERTER, VIN:2.3V TO 6V, VOUT: ADJ 0.6V TO 6V, SON6, SMD	TPS62290DRV1T	TEXAS INSTRUMENTS
Y1	1	32MHz		CRYSTAL, OSCILLATOR, 32MHz, -40DEGC/+125DEGC, SMD	NX2016SA 32.000MHz EXS00A-CS05931	NIHON DEMPYA KOGYO
Y2	1	32.768KHz		CRYSTAL, OSCILLATOR, 32.768KHz, -40DEGC/+125DEGC, SMD	NX3215SA 32.768KHz EXS00A-MU00301	NIHON DEMPYA KOGYO

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